



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-10-11
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement			
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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STP2NK90Z	TLDZ*EZ926W1	A	64BA	2017-10-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	TO 220 AB NON ISOL			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.53	Die back side metal - Leadframe metal	278
Lead	5.19	Soft solder	2730

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TLD2*E2926W1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.800	mg	supplier	die	Silicon (Si)	7440-21-3		5.598	mg	965172	2946
				supplier	metallization	Aluminium (Al)	7429-90-5		0.079	mg	13621	42
				supplier	Passivation	Silicon Nitride	12033-89-5		0.026	mg	4483	14
				supplier	Passivation	Silicon Oxide	7631-86-9		0.042	mg	7241	22
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	517	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.038	mg	6552	20
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.014	mg	2414	7
Leadframe	Copper & its alloys	1253.535	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.376	mg	998277	658618
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	1000	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	300	198
				supplier	metallization	Nickel (Ni)	7440-02-0		0.490	mg	391	258
Soft solder	Solder	5.432	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	5.187	mg	954897	2730
				supplier	solder	Silver (Ag)	7440-22-4		0.136	mg	25037	72
				supplier	solder	Tin (Sn)	7440-31-5		0.109	mg	20066	57
				supplier	metallization	Phosphorus (P)	12185-10-3		0.040	mg	32	21
Bonding wires	Other inorganic materials	0.147	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.146	mg	993197	77
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	6803	1
Encapsulation	Other Organic Materials	628.724	mg	supplier	mold compound	Silica, vitreous	60676-86-0		546.990	mg	870000	287889
				supplier	mold compound	Epoxy resin	25068-38-6		62.872	mg	99999	33091
				supplier	mold compound	Phenol resin	29690-82-2		15.718	mg	25000	8273
Connections coating	Solder	6.362	mg	supplier	mold compound	Carbon Black	1333-86-4		3.144	mg	5001	1655
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348